



Product Change Notification / RMES-04CXZS338

Date:

05-Oct-2022

Product Category:

Wireless Modules

PCN Type:

Silicon Die Revision

Notification Subject:

eSign # E000136811 Final Notice: Implement silicon revision C0 for WFI32E01xx device family and introduction of new software tool

Affected CPNs:

[RMES-04CXZS338_Affected_CPN_10052022.pdf](#)
[RMES-04CXZS338_Affected_CPN_10052022.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Silicon Die Revision

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Implement silicon revision C0 for WFI32E01xx device family and introduction of new software tool.

Pre and Post Change Summary:

	Pre Change	Post Change
CPN	Module variants with silicon revision B0 have	Both module variants with silicon revision C0 and B0 have below standard CPNs:

		WFI32E01PC-I
		WFI32E01PE-I
		WFI32E01UC-I
		WFI32E01UE-I
below standard CPNs:		MPLAB® Harmony 3 Chip Support Package (CSP) v3.13.1 and after is required to build the software for silicon revision C0
WFI32E01PC-I		Binary images built with CSP versions earlier than v3.13.1 must not be used with silicon revision (C0) and modules containing C0. Version 3.13.1 may be used with silicon version C0, B0, and older versions.
WFI32E01PE-I		
WFI32E01UC-I		
WFI32E01UE-I		

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To make sure the customers smoothly migrate their software to new silicon revision.

MPLAB® Harmony 3 Chip Support Package (CSP) v3.13.1 and after is required to build the software for silicon revision C0

Binary images built with CSP versions earlier than v3.13.1 must not be used with silicon revision (C0) and modules containing C0. Version 3.13.1 may be used with silicon version C0, B0, and older versions.

Details about MPLAB® Harmony 3 Chip Support Package (CSP) can be found in below link:

https://github.com/Microchip-MPLAB-Harmony/csp/blob/master/release_notes.md

Change Implementation Status:In Progress

Estimated First Ship Date:January 01, 2023 (date code: 2301)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	October 2022		January 2023
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Workweek	4 1	42	43	44	45		0 1	0 2	0 3	0 4	0 5
Final PCN Issue Date	X										
Estimated Implementation Date						X					

Method to Identify Change:Traceability code

Qualification Report:Not Applicable.

Revision History:

October 05, 2022: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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